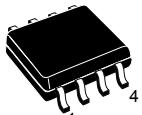


## N-channel 20 V, 30 mΩ typ., 6 A, 2.7 V drive, STripFET™ II Power MOSFET in an SO-8 package

### Features



SO-8

Order code	V <sub>DS</sub>	R <sub>Ds(on)</sub> max.	I <sub>D</sub>
STS6NF20V	20 V	40 mΩ (@4.5 V)	6 A
		45 mΩ (@2.7 V)	

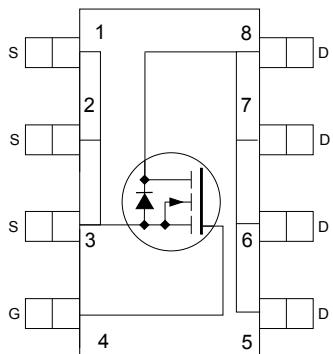
- Ultra low threshold gate drive
- 100% avalanche tested
- Low gate charge

### Applications

- Switching applications

### Description

This Power MOSFET series has been developed using STMicroelectronics' unique STripFET™ process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.



SC12830N

Product status link	
<a href="#">STS6NF20V</a>	
Product summary	
<b>Order code</b>	
Order code	STS6NF20V
<b>Marking</b>	6F20V-
<b>Package</b>	SO-8
<b>Packing</b>	Tape and reel

## 1 Electrical ratings

**Table 1.** Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	20	V
$V_{GS}$	Gate-source voltage	$\pm 12$	V
$I_D$	Drain current (continuous) at $T_{amb} = 25\text{ }^\circ\text{C}$	6	A
	Drain current (continuous) at $T_{amb} = 100\text{ }^\circ\text{C}$	3.8	A
$I_{DM}^{(1)}$	Drain current (pulsed)	24	A
$P_{TOT}$	Total dissipation at $T_{amb} = 25\text{ }^\circ\text{C}$	2.5	W
$T_{stg}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_j$	Operating junction temperature range		$^\circ\text{C}$

1. Pulse width limited by safe operating area.

**Table 2.** Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-amb}$	Thermal resistance junction-ambient	50	$^\circ\text{C/W}$

## 2 Electrical characteristics

$T_C = 25^\circ\text{C}$  unless otherwise specified

**Table 3. On-/off-states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}$ $V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}$ $T_C = 125^\circ\text{C}$ <sup>(1)</sup>			10	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			$\pm 100$	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DD} = V_{GS}, I_D = 250 \mu\text{A}$	0.6			V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$		30	40	$\text{m}\Omega$
		$V_{GS} = 2.7 \text{ V}, I_D = 3 \text{ A}$		37	45	
		$V_{GS} = 1.95 \text{ V}, I_D = 0.9 \text{ A}$			90	

1. Defined by design, not subject to production test.

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$g_{fs}$	Forward transconductance		6.5	10	15	S
$C_{iss}$	Input capacitance		320	460	640	pF
$C_{oss}$	Output capacitance	$V_{DS} = 15 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0 \text{ V}$	130	200	280	pF
$C_{rss}$	Reverse transfer capacitance		33	50	68	pF
$Q_g$	Total gate charge	$V_{DD} = 16 \text{ V}, I_D = 6 \text{ A}$	5.5	8.5	11.5	nC
$Q_{gs}$	Gate-source charge	$V_{GS} = 0 \text{ to } 4.5 \text{ V}$	1.2	1.8	2.5	nC
$Q_{gd}$	Gate-drain charge	(see <a href="#">Figure 12. Test circuit for gate charge behavior</a> )	1.6	2.4	3.4	nC

**Table 5. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 10 \text{ V}, I_D = 3 \text{ A},$	-	7	20	ns
$t_r$	Rise time	$R_G = 4.7 \Omega, V_{GS} = 4.5 \text{ V}$	-	33	45	ns
$t_{d(\text{off})}$	Turn-off delay time	(see <a href="#">Figure 11. Test circuit for resistive load switching times</a> and <a href="#">Figure 16. Switching time waveform</a> )	-	27	40	ns
$t_f$	Fall time		-	10	20	ns

**Table 6. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		6	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		24	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 6 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 6 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$ $V_{DD} = 10 \text{ V}, T_J = 150 \text{ }^\circ\text{C}$	-	26		ns
$Q_{rr}$	Reverse recovery charge	(see <a href="#">Figure 16. Switching time waveform</a> )	-	13		nC
$I_{RRM}$	Reverse recovery current		-	1		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1

## Electrical characteristics (curves)

Figure 1. Safe operating area

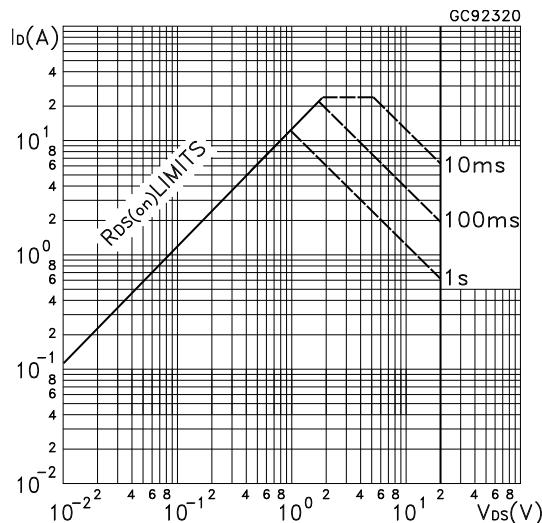


Figure 2. Thermal impedance

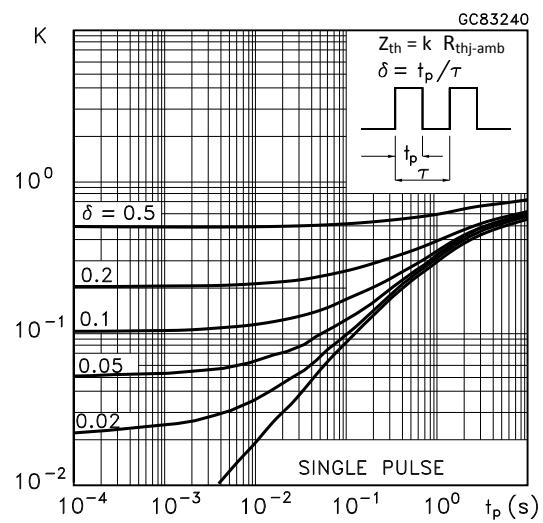


Figure 3. Output characteristics

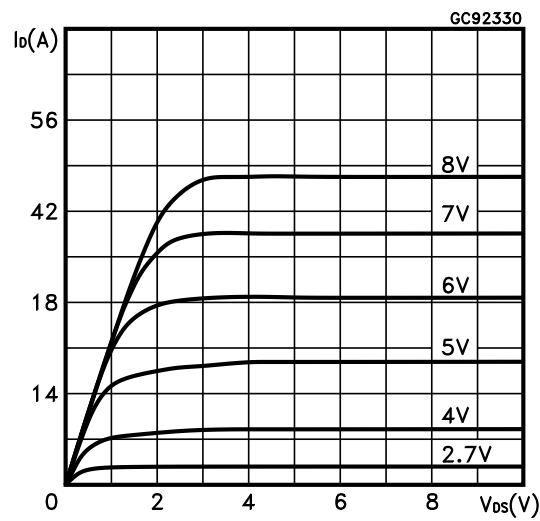
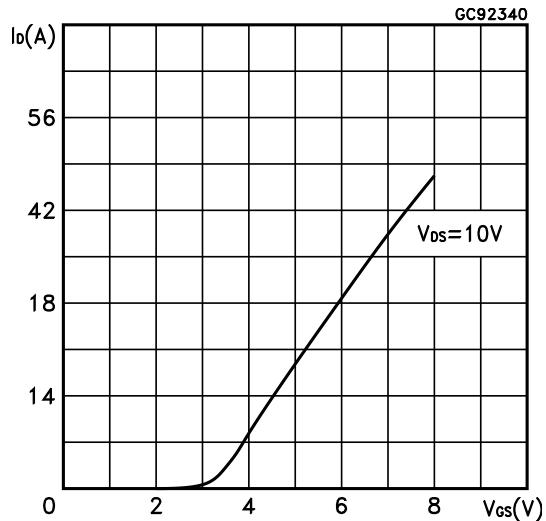
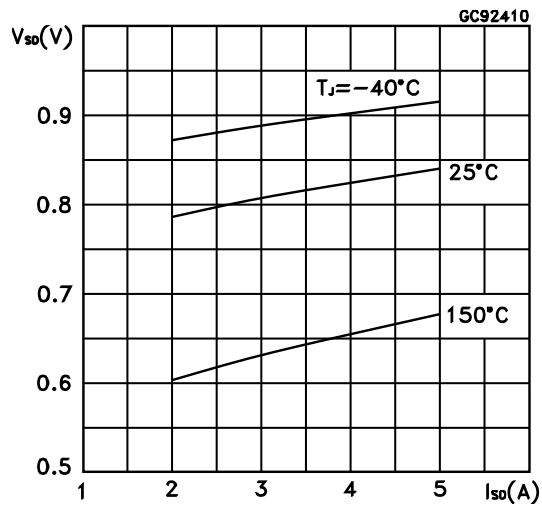
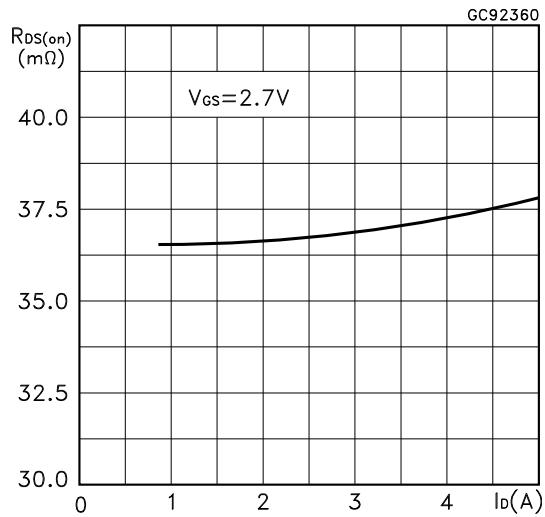
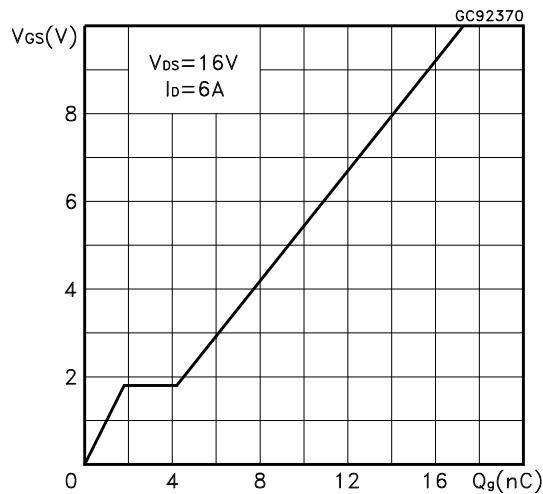
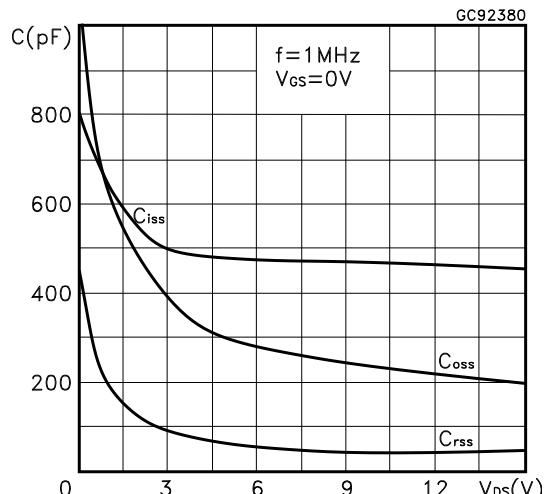
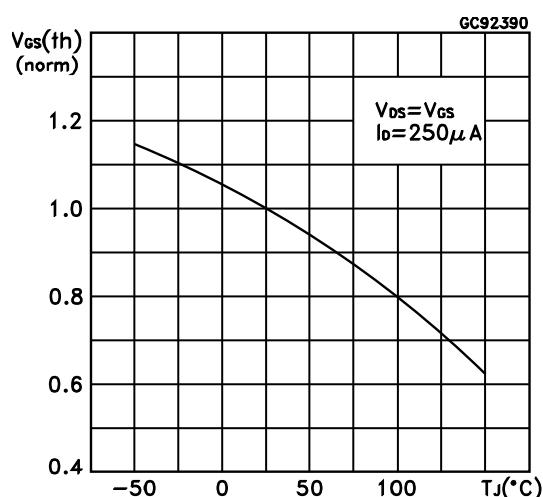
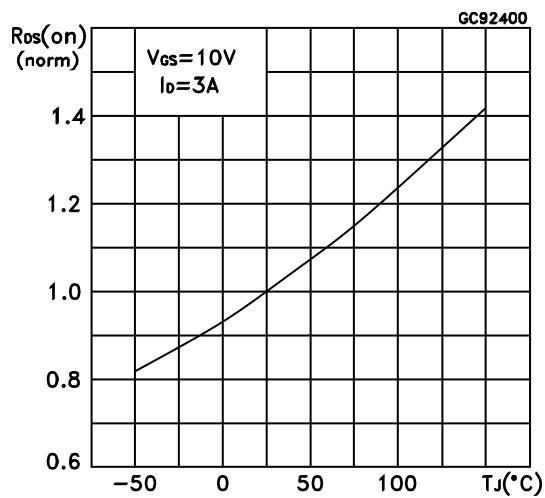


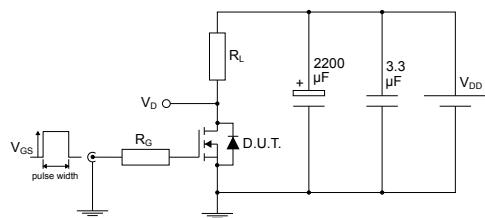
Figure 4. Transfer characteristics



**Figure 5. Source-drain diode forward characteristics**

**Figure 6. Static drain-source on-resistance**

**Figure 7. Gate charge vs gate-source voltage**

**Figure 8. Capacitance variations**

**Figure 9. Normalized gate threshold voltage vs temperature**

**Figure 10. Normalized on-resistance vs temperature**


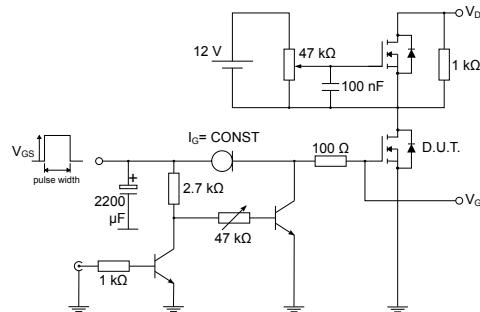
### 3 Test circuits

**Figure 11.** Test circuit for resistive load switching times



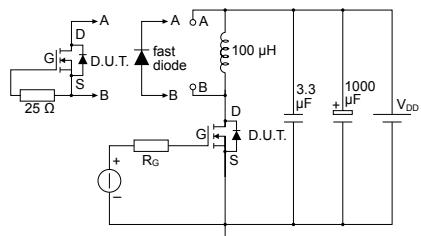
AM01468v1

**Figure 12.** Test circuit for gate charge behavior



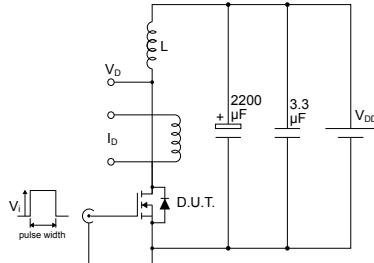
AM01469v1

**Figure 13.** Test circuit for inductive load switching and diode recovery times



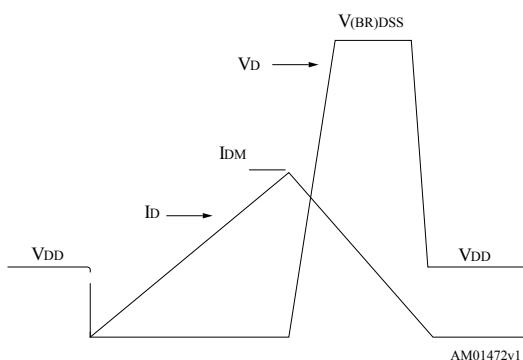
AM01470v1

**Figure 14.** Unclamped inductive load test circuit



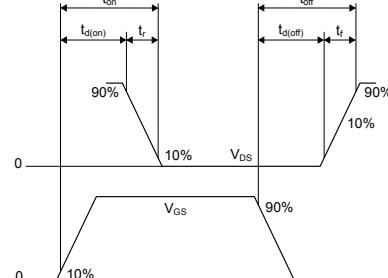
AM01471v1

**Figure 15.** Unclamped inductive waveform



AM01472v1

**Figure 16.** Switching time waveform



AM01473v1

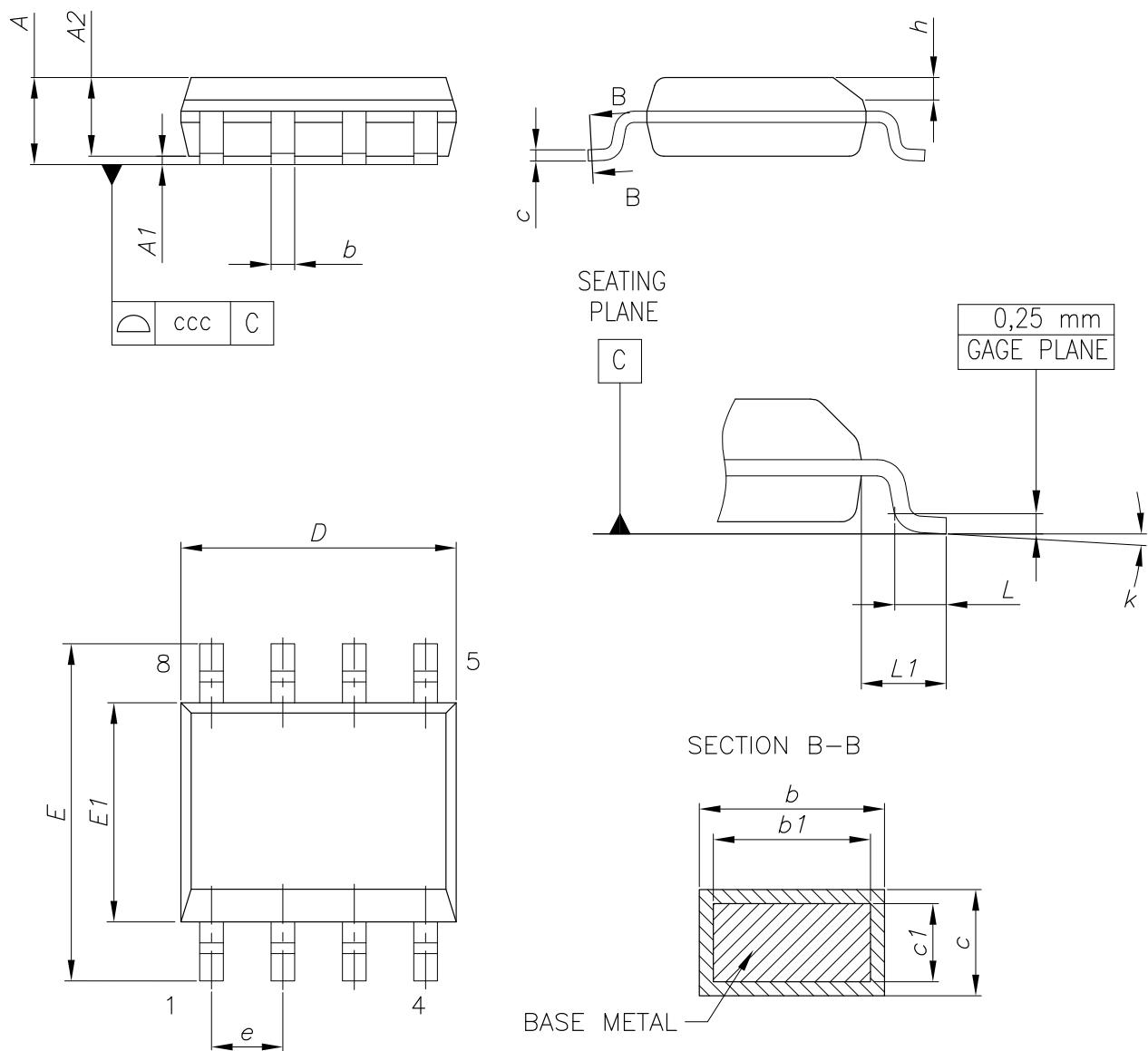
## 4

## Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

## 4.1 SO-8 package information

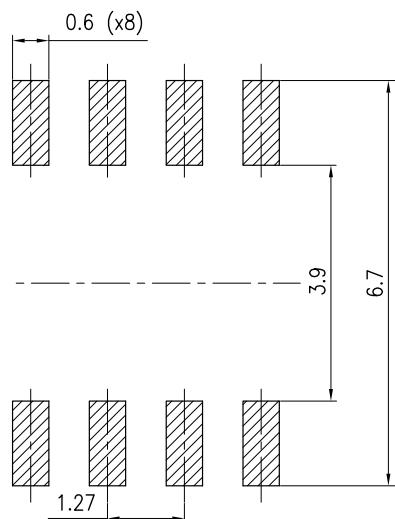
Figure 17. SO-8 package outline



0016023\_So-807\_fig2\_Rev10

**Table 7. SO-8 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
c	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10

**Figure 18. SO-8 recommended footprint (dimensions are in mm)**

0016023\_So-807\_footprint\_Rev10

## 4.2 SO-8 packing information

Figure 19. SO-8 tape and reel dimensions

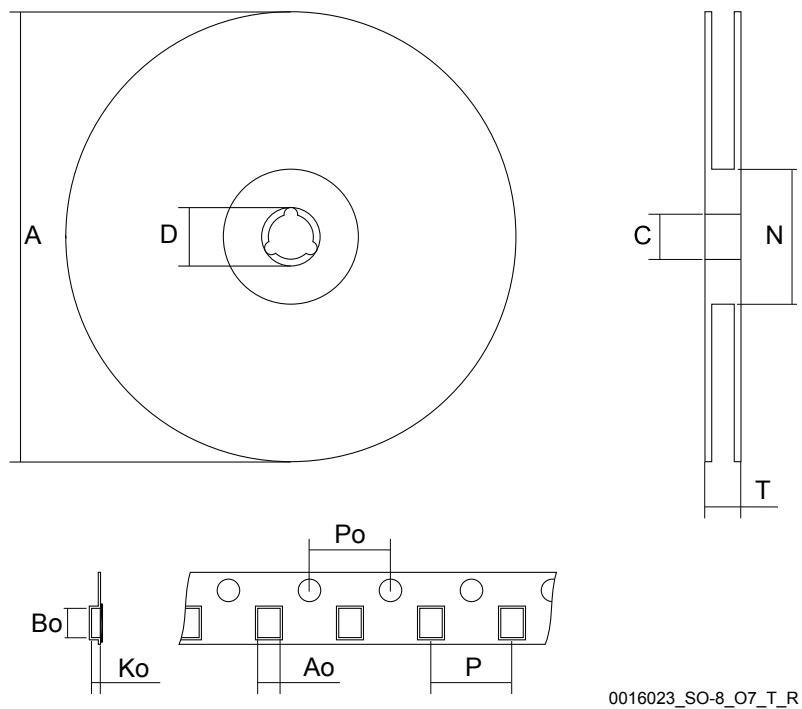


Table 8. SO-8 tape and reel mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			330
C	12.8		13.2
D	20.2		
N	60		
T			22.4
Ao	8.1		8.5
Bo	5.5		5.9
Ko	2.1		2.3
Po	3.9		4.1
P	7.9		8.1

## Revision history

**Table 9. Document revision history**

Date	Version	Changes
07-Feb-2008	1	Initial release.
18-Nov-2009	2	Added new RDS(on) value on <i>Table 4: On /off states</i>
29-Nov-2012	3	Max values have been added in <i>Table 5: Dynamic</i> and <i>Table 6: Switching times</i> . <i>Section 4: Package mechanical data</i> has been updated. Minor text changes.
04-Apr-2018	4	Removed maturity status indication from cover page. The document status is production data. Updated product marking on cover page. Updated <a href="#">Table 3. On-/off-states</a> . Updated <a href="#">Section 4 Package information</a> . Minor text changes

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